PRODUCT CHANGE NOTICE							
PART NUMBER(S):	PCN No.: 06-0130-04b						
Please see attachment.	DATE: March 7, 2006						
PART DESCRIPTION:	,						
Power Management and Interface Products – Change in Wafer Fabrication Site							
LEVEL OF CHANGE:							
[X] Level I, Customer Approval. [] Level II, Customer Information.							
PRODUCT ATTRIBUTE AFFECTED:							
[] Material Change[] Design Change[X] Process Change	[] Data Sheet Change[] Package Change[] Packing / Shipping						
[X] Other, Explain: Wafer Fabrication Site Transfer							
DESCRIPTION OF CHANGE:							
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry Episil. See attached Product List no. 04b.							
REASON FOR CHANGE:							
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.							
	PRODUCT CHARACTERIZATION COMPLETED AND SAMPLES* AVAILABLE (DATE): March 7, 2006						

^{*} Samples representative of product from the Product Family being transferred.



	PRODUCT CHANGE NOTICE						
	EST DATE OF PRODUCTI IENTS: 6/5/06	ION					
EFFEC	TIVITY CHANGE DATE O	R DATE CODE	: Work week assoc	iated wi	th earliest production shipment.		
[] S	STANDARD DISTRIBUTIO	N		[X]	CUSTOM DISTRIBUTION		
PERSO	ON TO CONTACT WITH Q	UESTIONS:					
Fred C	Claussen						
Sipex (ality Assurance and Reliabi Corporation Number: 408-935-7644 IMBER: 408-935-7678	lity					



PRODUCT CHANGE NOTICE

PCN No.: 06-0130-04b

List 4b

SP202ECN

SP202ECN-L

SP202ECP

SP202ECP-L

SP202ECT

SP202ECT-L

SP202EEN

SP202EEN-L

SP202EEP

SP202EEP-L

SP202EET

SP202EET-L

SP232ACN

SP232ACN-L

SP232ACP

SP232ACP-L

SP232ACT

SP232ACT-L

SP232AEN

SP232AEN-L

SP232AEP

SP232AEP-L

SP232AET

SP232AET-L

SP232ECN

SP232ECN-L

SP232ECP

SP232ECP-L

SP232ECT

SP232ECT-L SP232EEN

SP232EEN-L

SP232EEP

SP232EEP-L

SP232EET

SP232EET-L